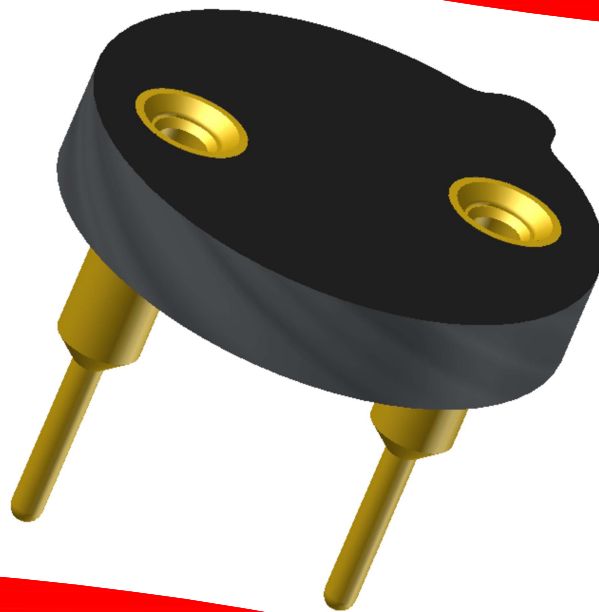




**HIGH RELIABILITY
OPTOELECTRONIC SOCKETS FOR
Innovative Sensor Technology IST AG**



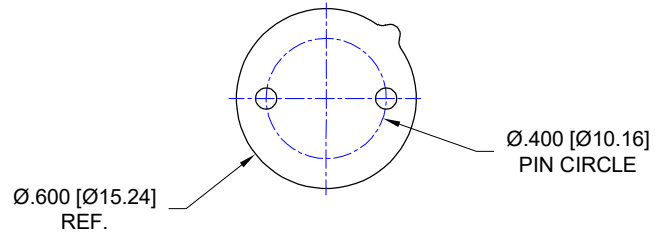
innovative
Sensor
Technology



Featuring Andon's Unique SenstacTM Contact

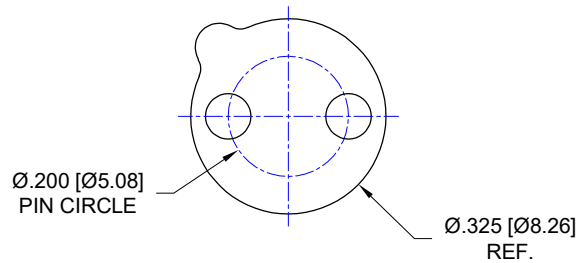
Innovative Sensor Technology IST AG

Innovative Sensor Technology AG			
IST AG Model Number	Andon Part Number Replace "XXX" with Terminal Type	Terminal Type	
		Thru-Hole	Surface Mount
HIS2000R-BWC300	R400-0802-01T-XXX-R27-L14	01S	93S
HIS2000R-O	R400-0802-01T-XXX-R27-L14	01S	93S
HIS2000R-A300-9	R400-0802-01T-XXX-R27-L14	01S	93S
HIS2000R-C300-6	R400-0802-01T-XXX-R27-L14	01S	93S
HIS2000R-0WC	R400-0802-01T-XXX-R27-L14	01S	93S
HIS2000R-C300-9	R400-0802-01T-XXX-R27-L14	01S	93S
HIS2000R-CWC300	R400-0802-01T-XXX-R27-L14	01S	93S



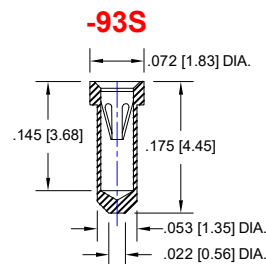
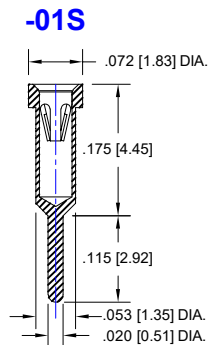
Thru-Hole: R400-0802-01T-01S-R27-L14
Surface Mount: R400-0802-01T-93S-R27-L14

Innovative Sensor Technology AG			
IST AG Model Number	Andon Part Number Replace "XXX" with Terminal Type	Terminal Type	
		Thru-Hole	Surface Mount
HIS550R-A	R200-0402-01T-XXX-R27-L14	01S	93S
HIS550R-OWC	R200-0402-01T-XXX-R27-L14	01S	93S
HIS550R-O	R200-0402-01T-XXX-R27-L14	01S	93S



Thru-Hole: R200-0402-01T-01S-R27-L14
Surface Mount: R200-0402-01T-93S-R27-L14

Terminals



Technical Information

Material:
Insulator: Hi-Temp UL 94V-O
Terminal: Brass, per ASTM-B16
Contact: BeCu, Per ASTM-B194

RoHS Compliant

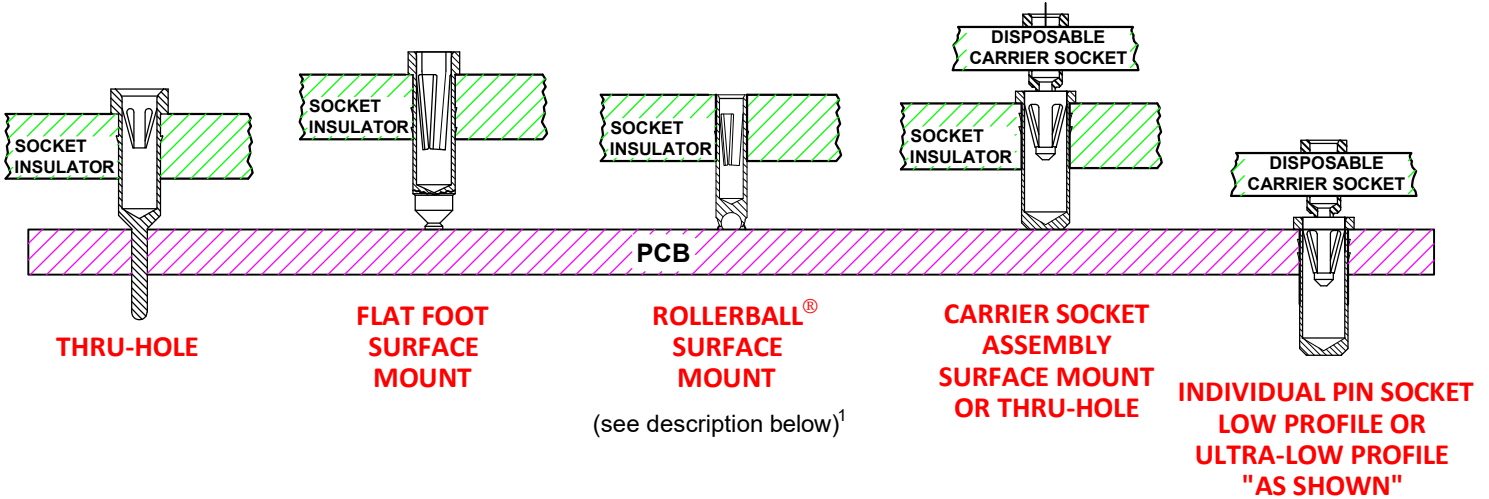
Plating:
R27 TERMINAL: GOLD / CONTACT: GOLD
OTHER PLATINGS AVAILABLE

Terminal Acceptance and Forces							
Thru Hole Terminals				Surface Mount Terminals			
Thru Hole Terminal	Accepts Pin Diameter	Insertion Force	Withdrawal Force	Surface Mount Terminal	Accepts Pin Diameter	Insertion Force	Withdrawal Force
-01S	Ø.018 [Ø0.46]	9.0 oz Avg.	2.0 oz Min	-93S	Ø.018 [Ø0.46]	9.0 oz Avg.	2.0 oz Min

Andon Proprietary Information

©Copyright 2026 Andon Electronics Corporation. All Rights Reserved. This material is protected under US and other copyrights and may not be copied, sold, or redistributed in any form without written permission of Andon Electronics Corporation. Copyrights and trademarks are property of their respective companies. We reserve the right to change specifications without notice. Andon makes no warranty, expressed or implied, as to the suitability of the sockets for the intended purpose.

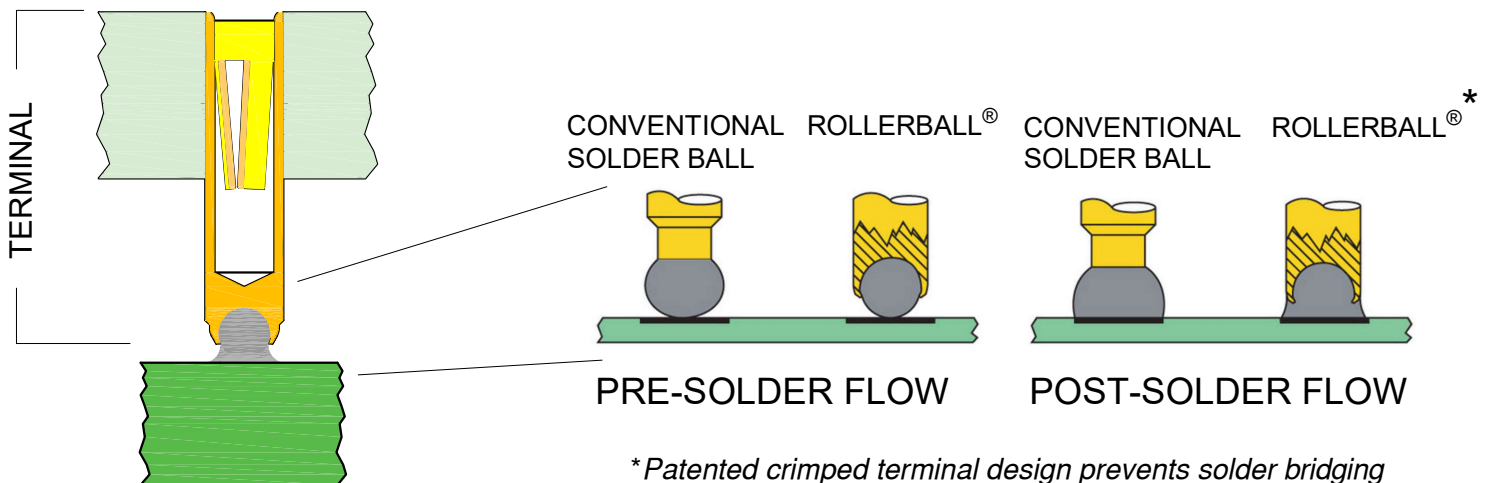
*Sockets are not drawn to scale Innovative Sensor Technology IST AG 05/12/2026



¹Andon's patented Rollerball® socket terminal option provides more accurate soldering, a stronger connection, and improved electrical connectivity - especially under shock and vibration - than other solder ball terminal designs. Better yet, it can enable you to avoid expensive rework and scrap - especially with larger PCBs where coplanarity is an inherent challenge.

The bottom of these terminals has a radiused hole, to prevent gas entrapment. The terminal is crimped over the solder ball beyond its hemisphere, encapsulating it - leaving just enough of the solder ball exposed to provide sufficient solder without the solder bridging common in conventional solder ball terminal designs.

With this unique design, the critical distance between the terminal and the PC board pad is typically reduced from .036"-.040" to .018"-.022". As such, the solder becomes part of the "anchor" cross-section - providing additional mechanical strength to the connection, as well as improved electrical connectivity. Because it also provides controlled dispersion of solder, this encapsulated solder ball reduces the risk of solder bridging inherent in conventional solder ball terminal designs.



For fast, accurate placement of SIP sockets and ultra-low profile terminals

Phase 1:
Receive Carrier Assemblies designed to your pin layout.



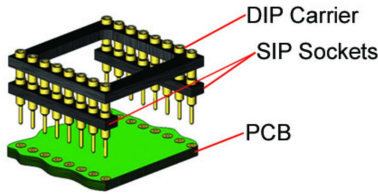
Phase 2:
Place carrier assemblies onto PCB; run through your soldering process.



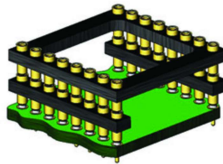
Phase 3:
Remove carrier and plug in your device; discard carrier or send back to our factory for reloading.

DIP

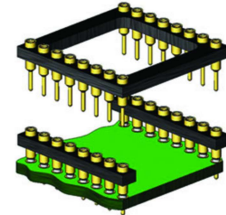
Before Soldering



During Soldering

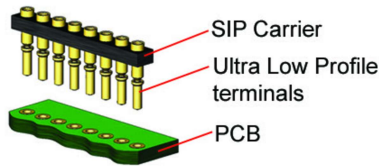


After Soldering

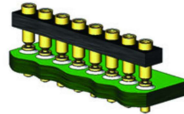


ULTRA-LOW PROFILE SIP

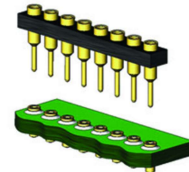
Before Soldering



During Soldering

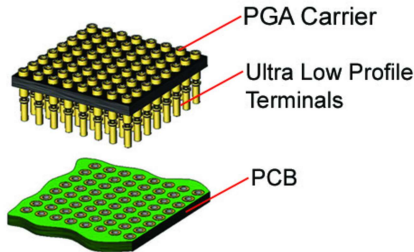


After Soldering

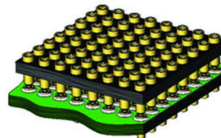


ULTRA-LOW PROFILE PGA

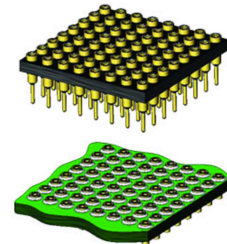
Before Soldering



During Soldering

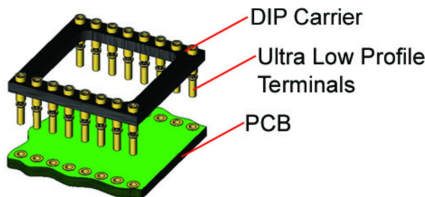


After Soldering

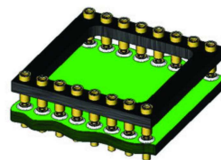


ULTRA LOW PROFILE DIP

Before Soldering



During Soldering



After Soldering

